

What is claimed is:

1. A semiconductor package with a heat spreader, comprising:

5           an upper PCB connected to a first chip;  
              a lower PCB connected to a second chip;  
              a heat spreader for spreading heat generated by the  
              first chip and the second chip to surroundings; and  
              thermally conductive members for transmitting the heat  
10          generated by the first chip and the second chip to the heat  
              spreader by connecting the heat spreader to the first chip  
              and the second chip.

2. The semiconductor package of claim 1, wherein the  
15          thermally conductive members are curved to form gaps between  
              the heat spreader and the first chip and between the heat  
              spreader and the second chip.

3. The semiconductor package of claim 1, wherein a space  
20          in the semiconductor package is filled with epoxy mold  
              compound ("EMC").

4. The semiconductor package of claim 1, wherein the  
thermally conductive members are disk-shaped metallic  
25          elastic bodies.

5. The semiconductor package of claim 4, wherein the thermally conductive members are disk springs.

6. A semiconductor package with a heat spreader,  
5 comprising:

a lead frame connected to a first chip;

a lower PCB connected to a second chip;

a heat spreader for spreading heat generated by the first chip and the second chip to surroundings; and

10 thermally conductive members for transmitting the heat generated by the first chip and the second chip to the heat spreader by connecting the heat spreader to the first chip and the second chip.

15 7. The semiconductor package of claim 6, wherein the thermally conductive members are curved to form gaps between the heat spreader and the first chip and between the heat spreader and the second chip.

20 8. The semiconductor package of claim 6, wherein a space in the semiconductor package is filled with epoxy mold compound ("EMC").

25 9. The semiconductor package of claim 6, wherein the thermally conductive members are disk-shaped metallic elastic bodies.

10. The semiconductor package of claim 9, wherein the thermally conductive members are disk springs.

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